



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-11-30
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacobello	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
------------------------------	------	----------------------------	----------

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STD110N8F6	TXDP*7D8GCC2	A	3068	2017-11-30
Amount	UoM	Unit type	ST ECOPACK Grade	
350.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	6.5-6.1-2.3	3	GULL WING	
Comment	0			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			TRUE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			FALSE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.14	Die - Leadframe	411
Lead	6.58	Soft solder	18811

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	TXDP17D8GCC2					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	2.975	mg	supplier	die	Silicon (Si)	7440-21-3		2.708	mg	910252	7737
				supplier	metallization	Aluminium (Al)	7429-90-5		0.071	mg	23866	203
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	2689	23
				supplier	Passivation	Silicon Nitride	12033-89-5		0.033	mg	11092	94
				supplier	Passivation	Silicon Oxide	7631-86-9		0.081	mg	27227	231
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.004	mg	1345	11
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.052	mg	17479	149
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.018	mg	6050	51
				supplier	alloy	Copper (Cu)	7440-50-8		164.152	mg	994601	469006
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.330	mg	1999	943
Leadframe	Copper & its alloys	165.043	mg	supplier	alloy	Cobalt (Co)	7440-48-4		0.462	mg	2799	1320
				supplier	metallization	Nickel (Ni)	7440-02-0		0.092	mg	559	263
				supplier	metallization	Phosphorus (P)	12185-10-3		0.007	mg	42	20
				supplier	solder	Lead (Pb)	7439-92-1	7a-Lead in high met	6.584	mg	955033	18811
				supplier	solder	Silver (Ag)	7440-22-4		0.172	mg	24950	491
Soft solder	Solder	6.894	mg	supplier	solder	Tin (Sn)	7440-31-5		0.138	mg	20017	394
				supplier	wire	Aluminium (Al)	7429-90-5		1.005	mg	996036	2871
				supplier	wire	Magnesium (Mg)	7439-95-4		0.004	mg	3964	11
Encapsulation	Other Organic Materials	173.034	mg	supplier	mold compound	Silica, vitreous	60676-86-0		151.405	mg	875001	432586
				supplier	mold compound	Tetramethyl-biphenyl-diyl-bis oxymethylene-bis	EC 413-900-7		6.921	mg	39998	19774
				supplier	mold compound	Epoxy Resin	25068-38-6		5.191	mg	30000	14831
				supplier	mold compound	phenol resin	29690-82-2		8.652	mg	50002	24720
				supplier	mold compound	Carbon black	1333-86-4		0.865	mg	4999	2471
Connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	2986